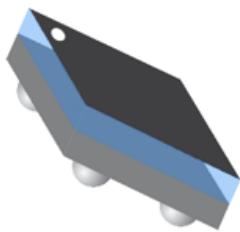


50 ohm nominal input / conjugate match to BlueNRG tranceiver, with integrated harmonic filter

Datasheet - production data

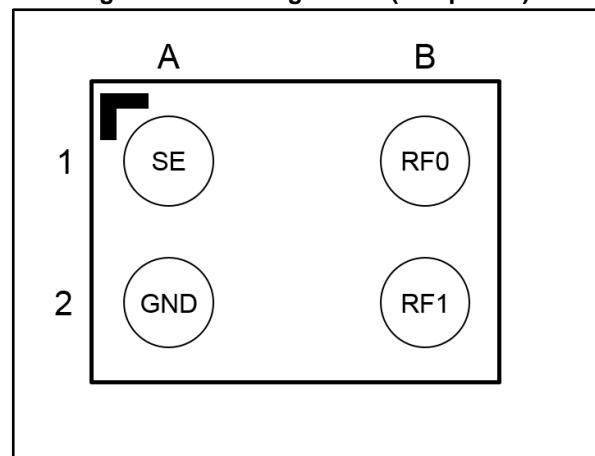


**Chip Scale package on glass
4 bumps - 1.4 x 0.85 mm²**

Description

This device is an ultra-miniature balun which integrates matching network and harmonics filter. Matching impedance has been customized for the BlueNRG ST transceiver. The BALF-NRG-02D3 uses STMicroelectronics IPD technology on non-conductive glass substrate which optimizes RF performance.

Figure 1: Pin configuration (bump view)



Features

- 50 Ω nominal input / conjugate match to BlueNRG device
- Low insertion loss
- Low amplitude imbalance
- Low phase imbalance

Benefits

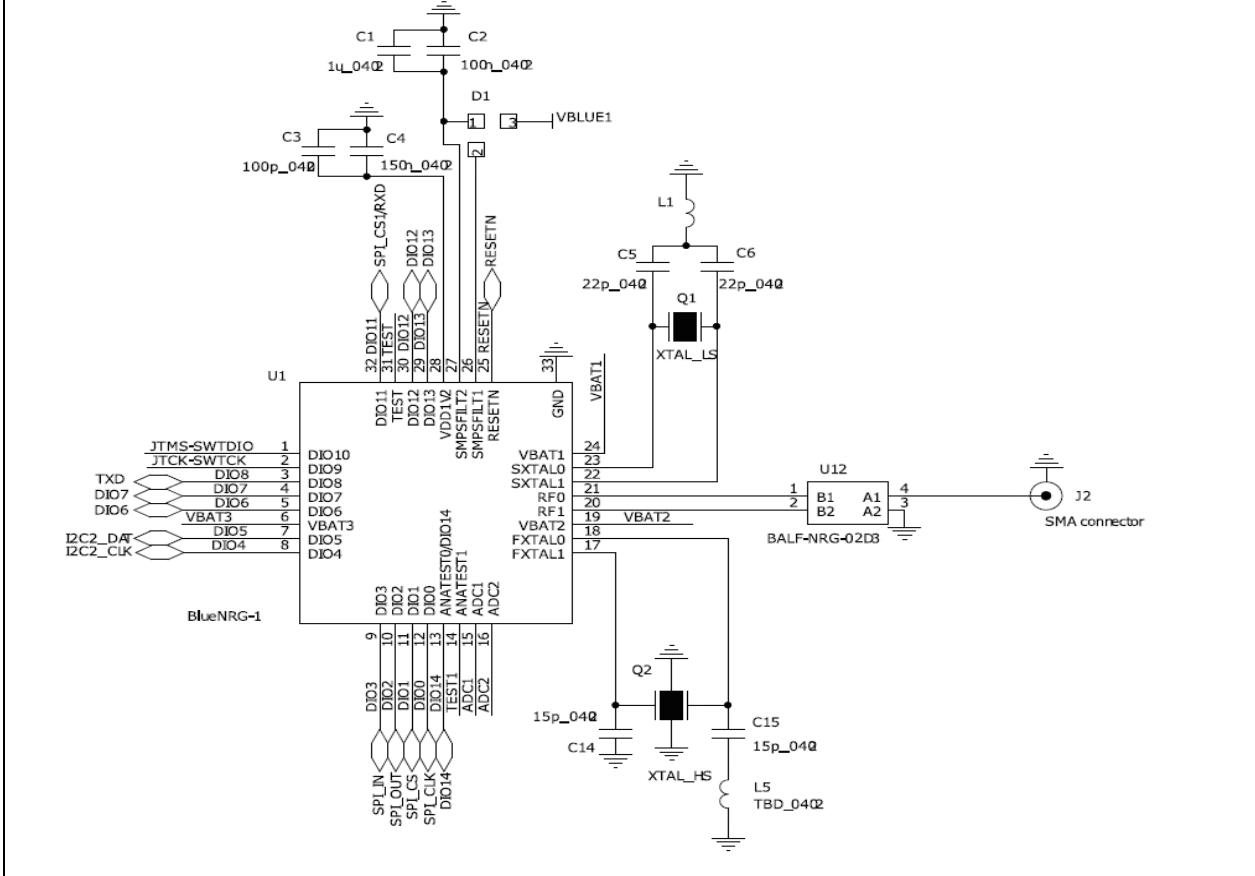
- Small footprint
- RF BOM reduction
- High RF performance

Applications

- Bluetooth low energy impedance matched balun filter
- Optimized for ST BlueNRG RFIC

1 Application schematic

Figure 2: Application diagram example (refer to BlueNRG reference design)



2 Characteristics

Table 1: Absolute maximum ratings (limiting values)

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
P_{IN}	Input power RFIN		-	10	dBm
V_{ESD}	ESD ratings human body model, all I/O one at a time while others connected to GND	2000	-		V
	ESD ratings machine model (MM: C = 200 pF, R = 25 Ω , L = 500 nH)	200	-		
T_{OP}	Operating temperature	-40	-	+105	°C

Table 2: Electrical characteristics ($T_{amb} = 25$ °C)

Symbol	Definition	Value			Unit
		Min.	Typ.	Max.	
Z_{diff}	Nominal differential impedance	Match to BlueNRG			Ω
Z_{ANT}	Nominal antenna impedance		50		Ω
f	Frequency range (bandwidth)	2400		2500	MHz
I_L	Insertion loss in bandwidth		1.33	1.85	dB
RL_{SE}	Single ended return loss in bandwidth	21	30		
RL_{DIFF}	Differential return loss in bandwidth	17	19		
H_2	Second harmonic attenuation (differential mode)	40	49		
H_3	Third harmonic attenuation (differential mode)	46	55		
H_4	Fourth harmonic attenuation (differential mode)	42	50		
H_5	Fifth harmonic attenuation (differential mode)	31	56		
H_6	Fifth harmonic attenuation (differential mode)	29	45		
H_7	Fifth harmonic attenuation (differential mode)	30	42		
Φ_{imb}	Output phase imbalance	-3.5	0	3.5	°
A_{imb}	Output amplitude imbalance	-1	0	1	dB

2.1 RF measurement

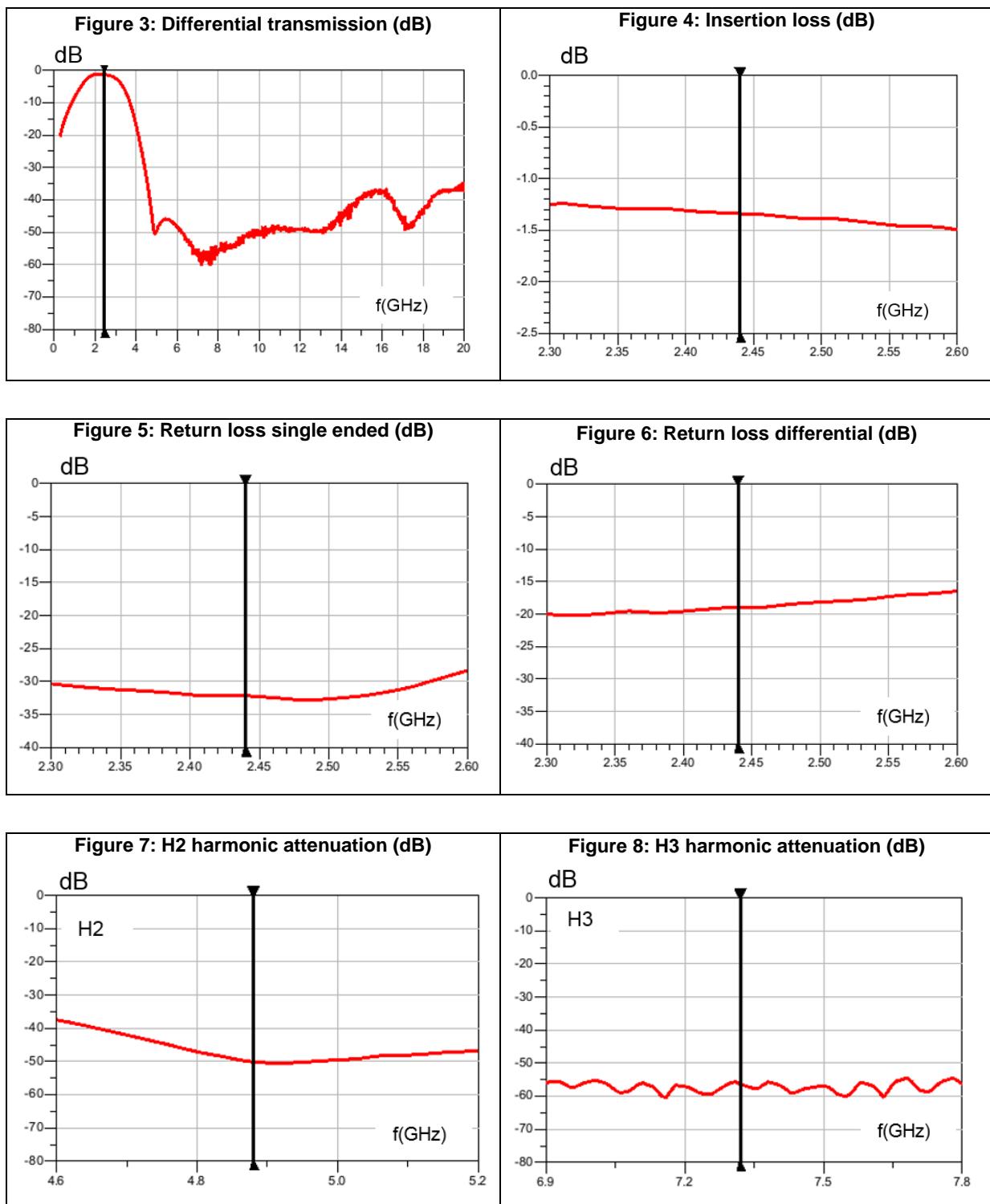


Figure 9: H4 harmonic attenuation (dB)

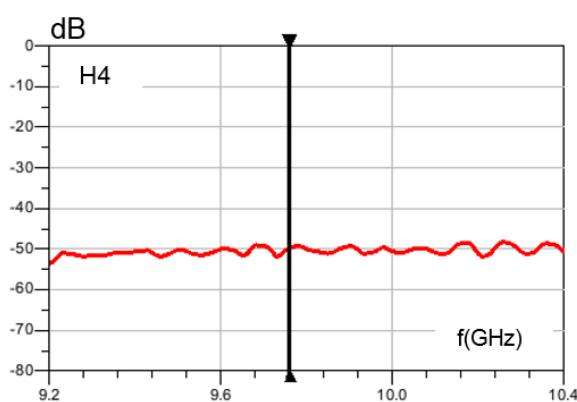


Figure 10: H5 harmonic attenuation (dB)

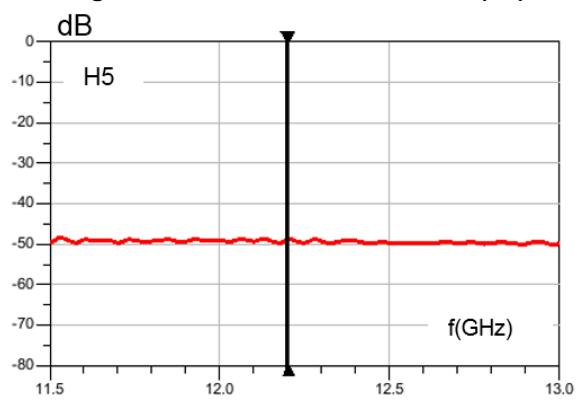


Figure 11: H6 harmonic attenuation (dB)

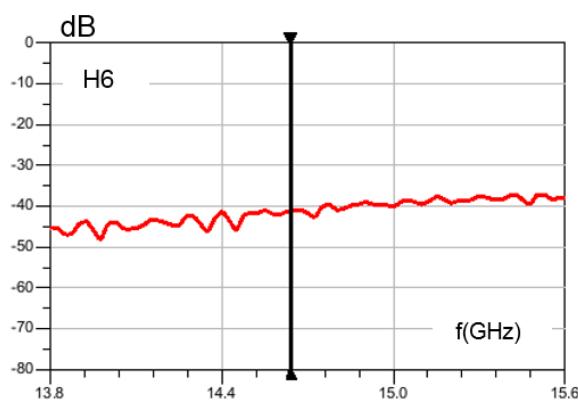


Figure 12: H7 harmonic attenuation (dB)

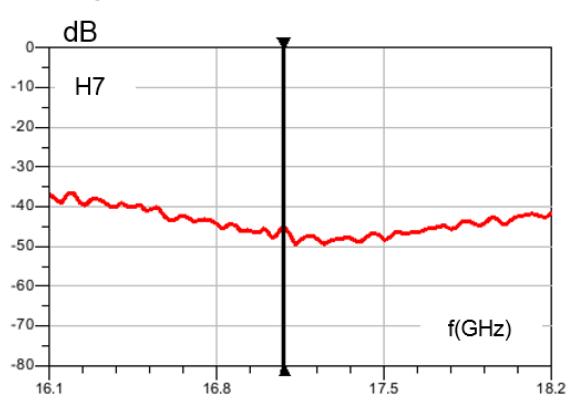


Figure 13: Amplitude imbalance in dB

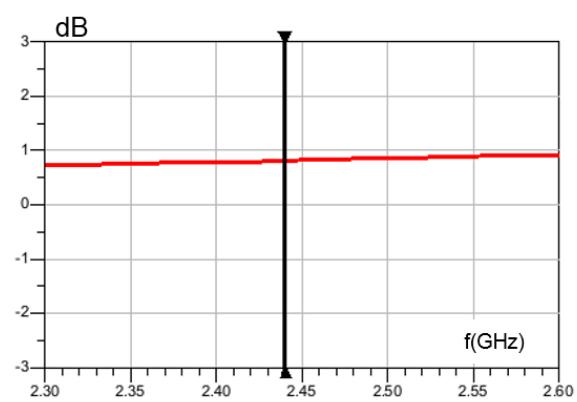
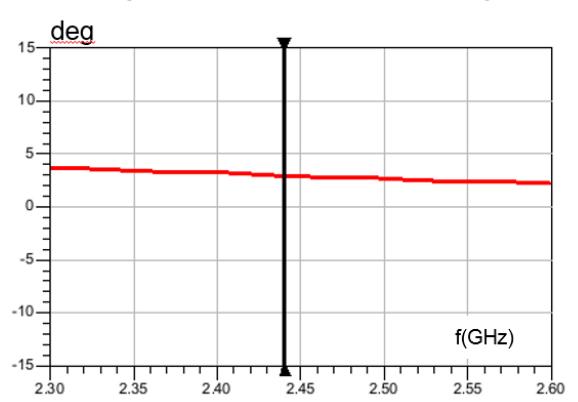


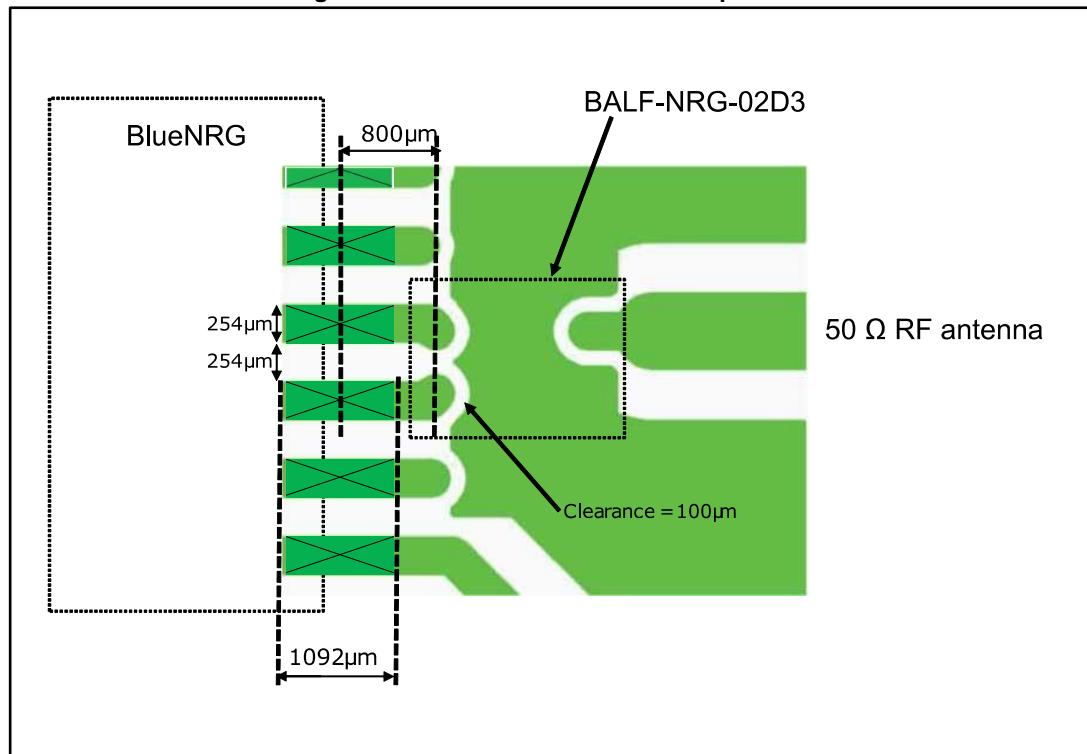
Figure 14: Phase imbalance in deg



3 Application information

3.1 BALF-NRG-02D3 with BlueNRG

Figure 15: Recommended balun land pattern



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 CSPG 0.4 package information

Figure 16: CSPG package outline (bump view)

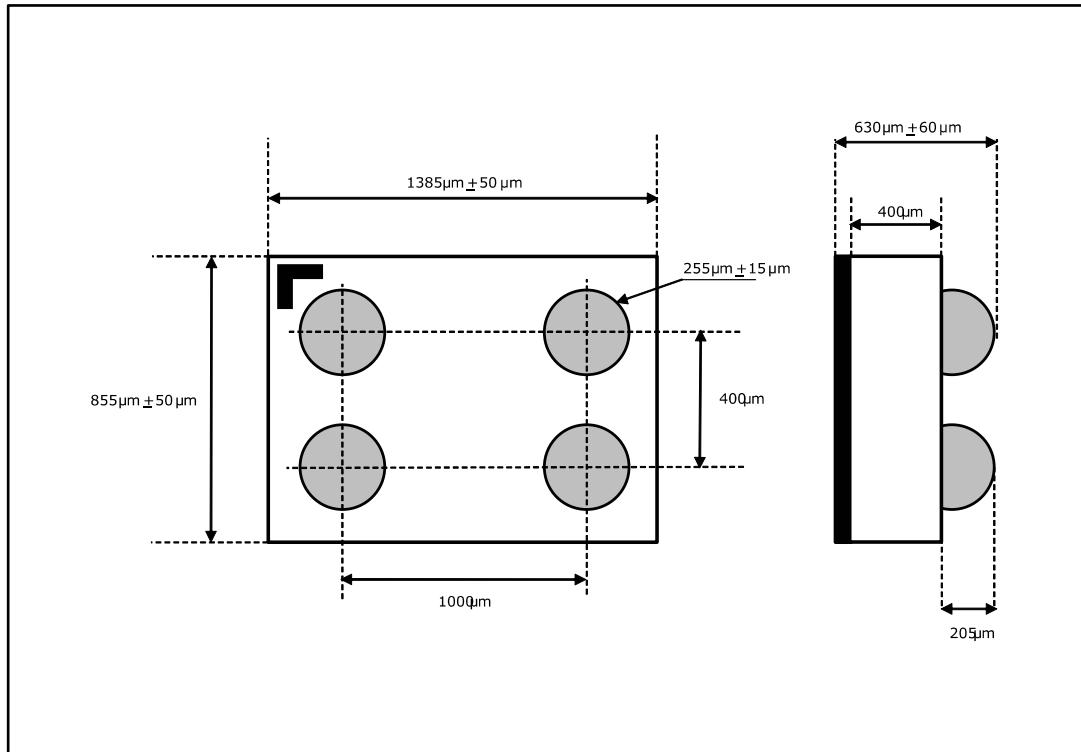


Figure 17: Footprint - 3 mils stencil -non solder mask defined

Copper pad diameter:
220 μ m recommended
180 μ m minimum
260 μ m maximum

Solder mask opening:
320 μ m recommended
300 μ m minimum
340 μ m maximum

Solder stencil opening:
220 μ m recommended

Figure 19: Footprint - 5 mils stencil -non solder mask defined

Copper pad diameter:
220 μ m recommended
180 μ m minimum
260 μ m maximum

Solder mask opening:
320 μ m recommended
300 μ m minimum
340 μ m maximum

Solder stencil opening:
330 μ m recommended*

*depending on paste, it can go down to 270 μ m

Figure 18: Footprint - 3 mils stencil - solder mask defined

Solder mask opening:
220 μ m recommended
180 μ m minimum
260 μ m maximum

Copper pad diameter:
320 μ m recommended
300 μ m minimum

Solder stencil opening:
220 μ m recommended

Figure 20: Footprint - 5 mils stencil - solder mask defined

Solder mask opening:
220 μ m recommended
180 μ m minimum
260 μ m maximum

Copper pad diameter:
320 μ m recommended
300 μ m minimum

Solder stencil opening:
330 μ m recommended*

*depending on paste, it can go down to 270 μ m

4.2 CSPG 0.4 packing information

Figure 21: Marking

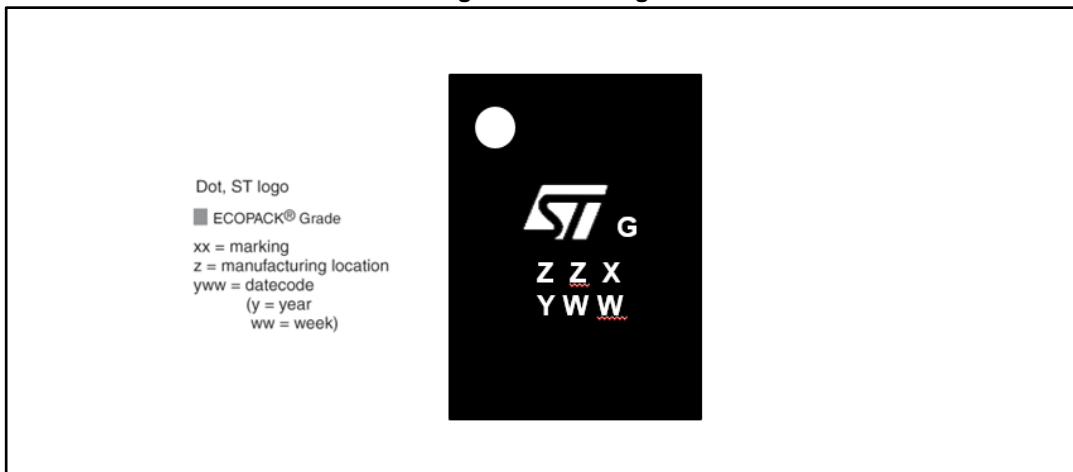
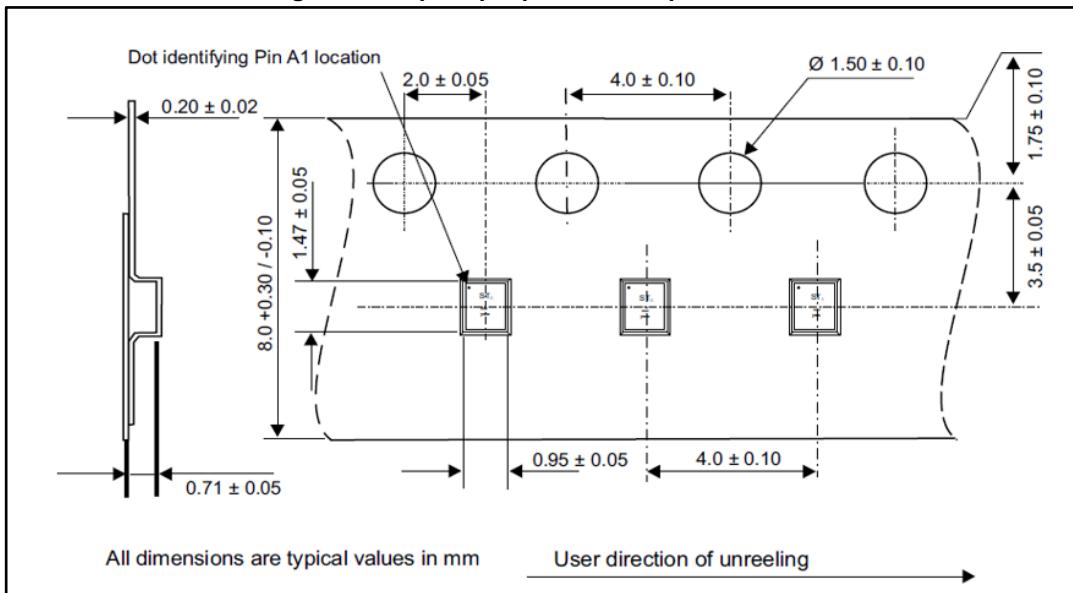


Figure 22: Flip Chip tape and reel specifications



More packing information is available in the application note:

- AN2348 Flip-Chip: "Package description and recommendations for use"

5 Ordering information

Figure 23: Ordering information scheme

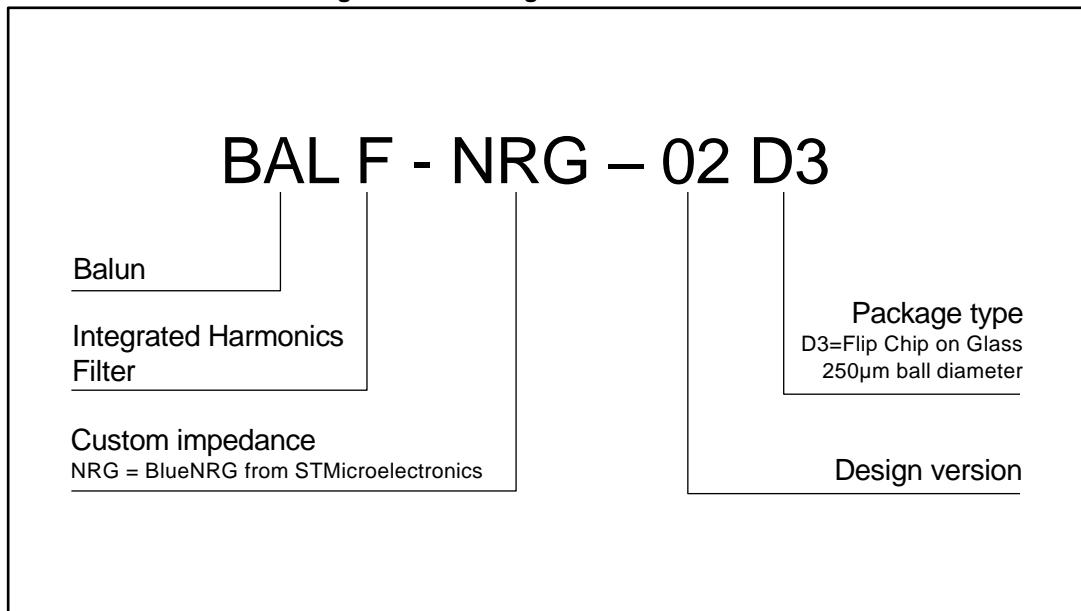


Table 4: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
BALF-NRG-02D3	TK	CSPG	1.37 mg	5000	Tape and reel

6 Revision history

Table 5: Document revision history

Date	Revision	Changes
23-Jun-2017	1	Initial release.

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